



# SDM03U40

SOD-523

Min

1.50

1.10

0.25

0.70

0.10

0.55

All Dimensions in mm

Max

1.70

1.30

0.35

0.90

0.20

0.65

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## SURFACE MOUNT SCHOTTKY BARRIER DIODE

CATHODE MARK

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## **Features**

- Low Forward Voltage Drop
- Guard Ring Die Construction for Transient Protection
- Ideal for low logic level applications
- Low Capacitance
- Lead Free by Design/RoHS Compliant (Note 1)
- "Green" Device, Note 4 and 5
- Qualified to AEC-Q101 Standards for High Reliability

### **Mechanical Data**

- Case: SOD-523
- Case Material: Molded Plastic, "Green" Molding Compound, Note 5. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminal Connections: Cathode Band
- Terminals: Finish Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Marking Code: LK
- Ordering Information: See Last Page
- Weight: 0.002 grams (approximate)

#### Maximum Ratings @ T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Reverse Voltage	V <sub>RM</sub>	40	V
DC Reverse Voltage	V <sub>R</sub>	30	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	21	V
Average Rectified Current	Ι <sub>Ο</sub>	30	mA
Non-Repetitive Peak Forward Surge Current @8.3ms Single half sine-wave superimposed on rated load	I <sub>FSM</sub>	200	mA

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MARKING CODE

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 2)	Pd	150	mW
Thermal Resistance, Junction to Ambient (Note 2)	$R_{ ext{ heta}JA}$	667	°C/W
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>	-40 to +125	٥C

## Electrical Characteristics @ T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Breakdown Voltage (Note 3)	V <sub>(BR)R</sub>	40			V	I <sub>R</sub> = 10uA
Forward Voltage	VF		290	370	mV	I <sub>F</sub> = 1mA
Peak Reverse Current (Note 3)	IR			0.5	μA	V <sub>R</sub> = 30V
Total Capacitance	CT	—	2		pF	V <sub>R</sub> = 1V, f = 1.0 MHz

Note: 1. No purposefully added lead.

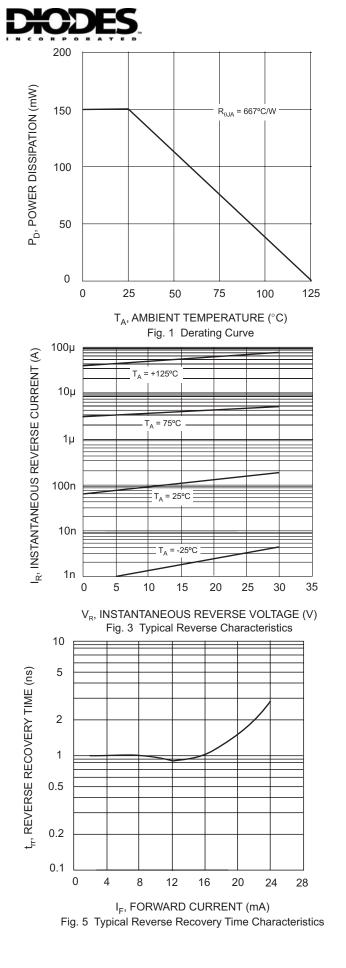
2. Part mounted on FR-4 board with recommended pad layout, which can be found on our website

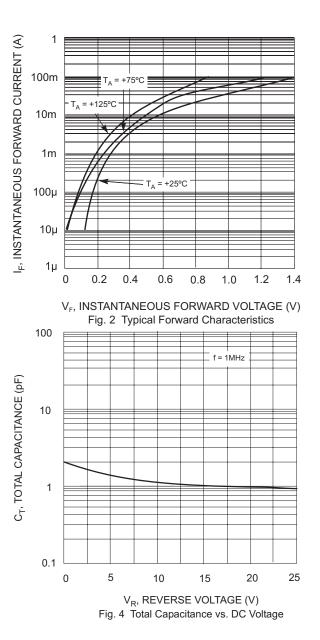
at http://www.diodes.com/datasheets/ap02001.pdf.  $T_A = 25^{\circ}C$ .

3. Short duration pulse test used to minimize self-heating effect.

4. Diodes Inc.'s "Green" Policy can be found on our website at http://www.diodes.com/products/lead\_free/index.php.

 Product manufactured with date code 0609 (week 9, 2006) and newer are built with Green Molding Compound. Product manufactured prior to date code 0609 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.







## Ordering Information (Note 5 & 6)

Device	Packaging	Shipping
SDM03U40-7	SOD-523	3000/Tape & Reel
SDM03U40-76K	SOD-523	6000/Tape & Reel

Note: 5. Product manufactured with date code 0609 (week 9, 2006) and newer are built with Green Molding Compound. Product manufactured prior to date code 0609 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

6. For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

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